

line 10, insert --insulative-- before
"inorganic".

Claim 4, line 7, insert --insulative-- before
"inorganic".

Claim 7, line 2, delete "first" and insert --third--;
line 4, delete "second" and insert --fourth--.

Claim 13, line 2, delete "any one of claims 7, 9 or 11"
and insert --claim 7--;

line 6, insert --insulative-- before
"inorganic".

Claim 14, line 2, delete "any one of claims 1, 2, 3, 4 or
13" and insert --claim 1--;
line 3, insert --insulative-- before
"inorganic".

Claim 15, line 2, delete "any one of claims" and insert
--claim--, same line 2, delete "to 14".

Claim 16, line 2, delete "any one of claims 1, 2, 3, 4,
13 or 14" and insert --claim 1--;
line 5, insert --insulative-- before
"inorganic".

Claim 17, line 2, delete "any one of claims 1 to 16" and

insert --claim 1--.

Claim 18, line 2, delete "any one of claims 1 to 17" and
insert --claim 1--.

Claim 19, line 2, delete "any one of claims 1 to 18" and
insert --claim 1--.

Claim 21, line 2, delete "any one of claims 1 to 20" and
insert --claim 1--.

Claim 22, line 15, delete "any one of claims 1 to 21" and
insert --claim 1--.

Please cancel claims 23-25 without prejudice or
disclaimer.

Claim 26, line 12, delete "or 3".

Claim 27, line 11, delete "any one";
line 12, delete "of claims 7 to 13" and insert
--claim 7--.

Please add the following new claims to the application:

--28. A circuit board comprising:

a first circuit member, which is an inorganic
insulating substrate, having a first connecting terminal; and

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Cont.

 a second circuit member, which is an organic insulating substrate, having a second connecting terminal; said first connecting terminal and the second connecting terminal being disposed facing each other, and an adhesive being put between the first connecting terminal and the second connecting terminal which are disposed facing each other; and

 said first connecting terminal and the second connecting terminal disposed facing each other being electrically interconnected by pressing;

 said adhesive being the adhesive for bonding circuit members according to claim 2; and

 at least any of the first adhesive layer stands adhered on the side of said first circuit member.

29. The circuit board according to claim 28, wherein the first circuit member is a semiconductor chip.

30. A circuit board comprising:

 a first circuit member, which is an inorganic circuit member, having a first connecting terminal; and

 a second circuit member, which is an organic circuit member, having a second connecting terminal;

 said first connecting terminal and the second connecting terminal being disposed facing each other, and an adhesive being put between the first connecting terminal and the second connecting terminal which are disposed facing each other; and